

Complementary pair with KSD1616(A).

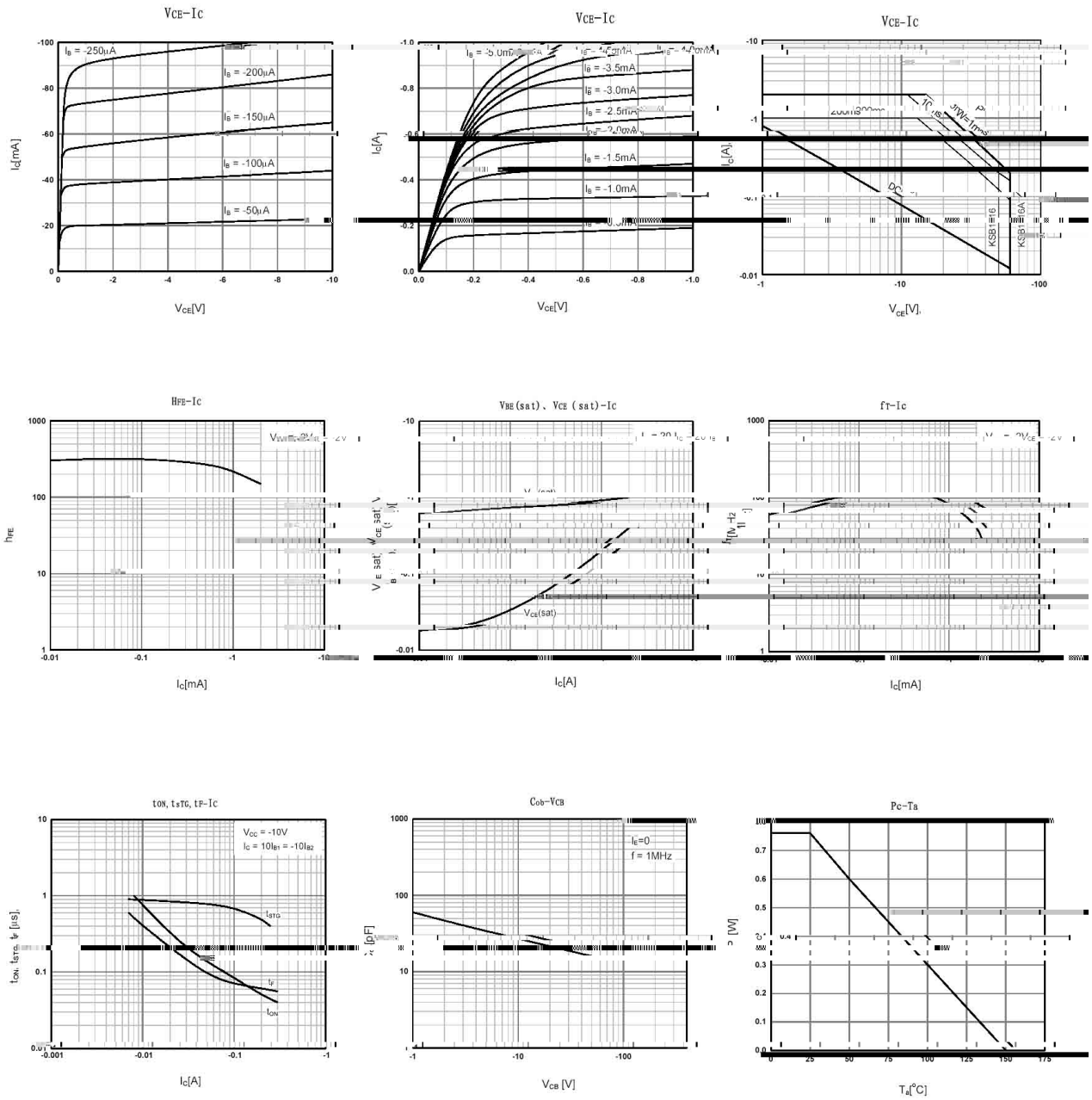


PIN1 χ Base PIN 2 χ Collector PIN 3 χ Emitter

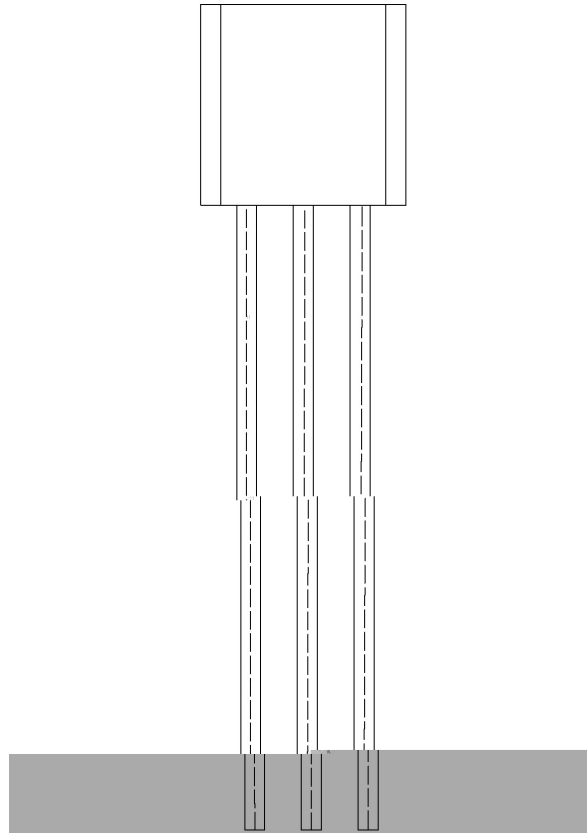
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	KSB1116 -60	V
		KSB1116A -120	
Collector to Emitter Voltage	V_{CEO}	KSB1116 -50	V
		KSB1116A -60	
Emitter to Base Voltage	V_{EBO}	-6.0	V
Collector Current - Continuous	I_C	-1.0	A
Base Current – Continuous	I_B	-2.0	A
Collector Power Dissipation	P_C	750	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-60V$ $I_E=0$			-0.1	μA
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=-6.0V$ $I_C=0$			-0.1	μA
DC Current Gain	$h_{FE(1)}$	KSB1116 $V_{CE}=-2.0V$ $I_C=-100mA$	135		600	

/ Electrical Characteristic Curve



/ Marking Instructions



б " X

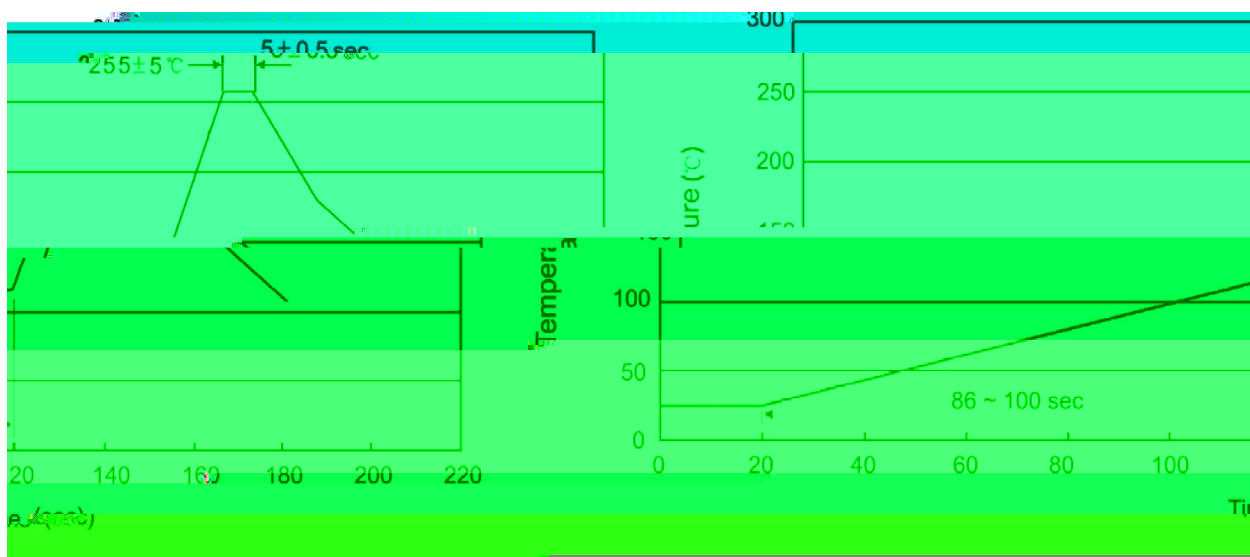
EU:

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() / Temperature Profile for Dip Soldering(Pb-Free)



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1. 1. 25~150 °C, Time: 60~90sec;
2. 2. 255±5 °C, Duration: 5±0.5sec;
3. 3. Cooling Speed: 2~10 °C/sec.

Note:

1. Preheating: 25~150 °C, Time: 60~90sec.
2. Peak Temp.: 255±5 °C, Duration: 5±0.5sec.
3. Cooling Speed: 2~10 °C/sec.

/ Resistance to Soldering Heat Test Conditions

□ °C 270±5 °C, Time: 10±1 sec. Temp: 270±5 Time: 10±1 sec

/ Packaging SPEC.

“Q” T Y E / BULK

Package Type	Units	Dimension 314	0
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